

## ABSTRACT

A bump forming method and apparatus by which no deformed bump having an abnormal shape is formed and no shape correcting process is necessary, the member for  
5 handling the bump materials can be easily changed, and the position of the member after the change of the member can be easily adjusted with a desired accuracy, thereby shortening the bump forming process and reducing the manufacturing cost.

A positioning member is set above a heating device. Bump materials are inserted into positioning holes of the positioning member and are made to partially protrude from the  
10 holes toward a side opposite to the heating device. A semiconductor substrate is positioned onto the positioning member so that the semiconductor substrate faces the protruding side of the bump materials. The bump materials are heated and pressed from the protruding side via the semiconductor substrate so as to form bumps having a specific shape.